



S2AF THRU S2MF

Surface Mount General Purpose Silicon Rectifiers

Reverse Voltage - 50 to 1000 V

Forward Current - 2 A

FEATURES

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Lead free in comply with EU RoHS 2011/65/EU directive

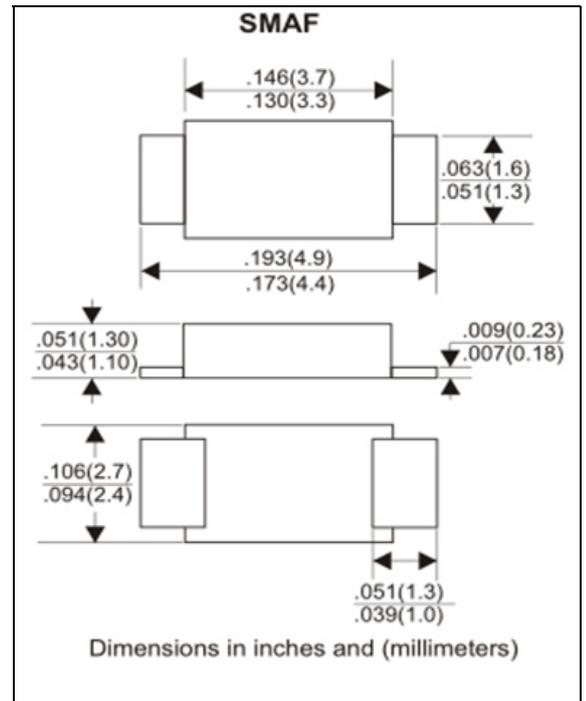
MECHANICAL DATA

- Case: SMAF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 27mg 0.00095oz

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.



Parameter	Symbols	S2AF	S2BF	S2DF	S2GF	S2JF	S2KF	S2MF	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_a = 65\text{ }^\circ\text{C}$	$I_{F(AV)}$	2							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	55							A
Maximum Instantaneous Forward Voltage at 2 A	V_F	1.1							V
Maximum DC Reverse Current at Rated DC Blocking Voltage $T_a = 25\text{ }^\circ\text{C}$ $T_a = 125\text{ }^\circ\text{C}$	I_R	5 100							μA
Typical Junction Capacitance ¹⁾	C_j	30							pF
Typical Thermal Resistance ²⁾	$R_{\theta JA}$	85							$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							$^\circ\text{C}$

1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

2) P.C.B. mounted with 0.2 X 0.2" (5 X 5 mm) copper pad areas.



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Fig.1 Forward Current Derating Curve

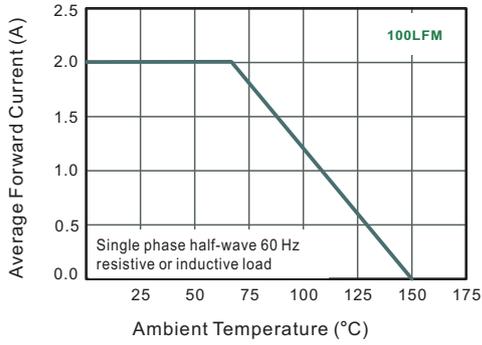


Fig.2 Typical Instantaneous Reverse Characteristics

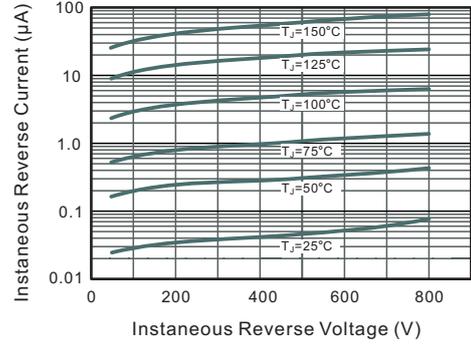


Fig.3 Typical Forward Characteristic

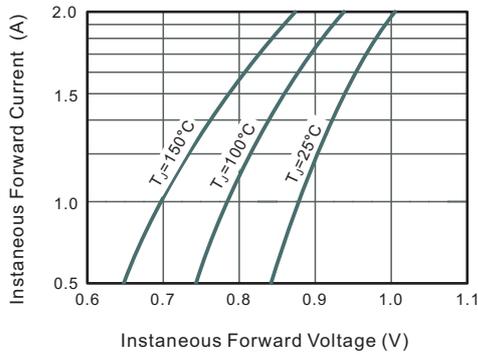


Fig.4 Typical Junction Capacitance

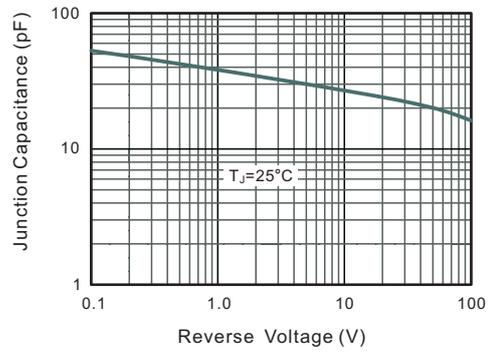


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current

